

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP92P H6327	**Issued**	31. March 2021
MA#	MA001096072		
Package	PG-SOT223-4-21	**Weight***	113.50 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.008	0.01		69	
	noble metal	gold	7440-57-5	0.031	0.03		269	
	inorganic material	silicon	7440-21-3	0.346	0.31	0.35	3051	3389
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		447	
	non noble metal	chromium	7440-47-3	0.152	0.13		1340	
	non noble metal	copper	7440-50-8	50.489	44.49	44.67	444858	446734
wire	non noble metal	copper	7440-50-8	0.018	0.02	0.02	158	158
encapsulation	organic material	carbon black	1333-86-4	0.604	0.53		5323	
	plastics	epoxy resin	-	9.062	7.98		79845	
	inorganic material	silicondioxide	60676-86-0	50.747	44.71	53.22	447132	532300
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12899	12899
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4520	4520
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com